

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S70	9795	(lid cover) with (recess\$3 open\$3 depress\$3 hole\$1 groove\$1) with (device chip die IC circuit) with (substrate carrier wafer)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/27 08:05
S71	28168864	@ad<"20040316"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/27 08:07
S72	6690	S70 and S71	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/27 08:07
S73	1656	(lid cover) with engag\$3 with attach\$4 with detach \$4	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/27 08:09
S74	6	S72 and S73	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/27 08:09
S75	970	S73 and S71	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/27 08:10
S76	1583087	(device chip die IC circuit) with (substrate PCB board wafer)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/27 08:11
S77	74	S75 and S76	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/27 08:11
S78	1478	(lid cover) near (recess\$3 open\$3 depress\$3 hole\$1 groove\$1) with (device chip die IC circuit) with (substrate carrier wafer)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/27 10:21

S79	28168864	@ad<"20040316"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/27 11:36
S80	1478	(lid cover) near (recess\$3 open\$3 depress\$3 hole\$1 groove\$1) with (device chip die IC circuit) with (substrate carrier wafer)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/27 11:36
S81	1039	S80 and S79	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/27 11:36
S82	299	S81 and (solder ball\$1 bump\$1)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/27 11:38
S83	17	("20020185748" "20030183909" "4801998" "5518660" "5796582" "5909056" "6278182" "6282096" "6317326" "6369380" "6392890" "6407461" "6515360" "6535388" "6549407" "6603183" "6654248").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/02/27 11:58
S84	8	("20040012094" "20040164390" "20040183556" "6479903" "6503776" "6693362" "6693364" "6713856").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/02/27 12:00
S85	4	("4744008" "5562971" "5931222" "6324067"). PN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/02/27 12:04
S86	1040	257/704.ccls.	US-PGPUB; USPAT; USOCR	OR	ON	2008/02/27 12:17
S87	781	S86 and S79	US-PGPUB; USPAT; USOCR	OR	ON	2008/02/27 12:18
S88	3	("4580157" "4975762" "5268533").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/02/27 13:02
S89	236	257/660.ccls.	US-PGPUB; USPAT; USOCR	OR	ON	2008/02/27 13:21
S90	429	257/710.ccls.	US-PGPUB; USPAT; USOCR	OR	ON	2008/02/27 13:35

S91	277	S90 and S79	US-PGPUB; USPAT; USOCR	OR	ON	2008/02/27 13:35
S92	1323	257/E23.114.ccls.	US-PGPUB; USPAT; USOCR	OR	ON	2008/02/27 13:40
S93	1013	S92 and S79	US-PGPUB; USPAT; USOCR	OR	ON	2008/02/27 13:40
S94	1093	257/E23.193.ccls.	US-PGPUB; USPAT; USOCR	OR	ON	2008/02/27 13:51
S95	857	S94 and S79	US-PGPUB; USPAT; USOCR	OR	ON	2008/02/27 13:51
S96	28168864	@ad<"20040316"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/27 16:38
S97	1040	257/704.ccls.	US-PGPUB; USPAT; USOCR	OR	ON	2008/02/27 16:38
S98	781	S97 and S96	US-PGPUB; USPAT; USOCR	OR	ON	2008/02/27 16:38
S99	236	257/660.ccls.	US-PGPUB; USPAT; USOCR	OR	ON	2008/02/27 16:38
S100	429	257/710.ccls.	US-PGPUB; USPAT; USOCR	OR	ON	2008/02/27 16:38
S101	1323	257/E23.114.ccls.	US-PGPUB; USPAT; USOCR	OR	ON	2008/02/27 16:38
S102	1093	257/E23.193.ccls.	US-PGPUB; USPAT; USOCR	OR	ON	2008/02/27 16:38
S103	3307	S102 S101 S100 S99 S98	US-PGPUB; USPAT; USOCR	OR	ON	2008/02/27 16:38
S104	3407	(lid cover) with attach\$4 with detach\$4 with (device chip die IC circuit)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/27 16:40
S105	8	S103 and S104	US-PGPUB; USPAT; USOCR	OR	ON	2008/02/27 16:40
S106	22555	(lid cover) with attach\$4 with detach\$4	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/27 16:41
S107	16	S103 and S106	US-PGPUB; USPAT; USOCR	OR	ON	2008/02/27 16:41

S108	21	("4187868" "4208577" "4742182" "4760440" "4899118" "5087964" "5107328" "5321204" "5352852" "5357056" "5384689" "5600541" "5729038" "5773323" "5863810" "5949655" "5951813" "6020629" "6025213" "6025767" "6198792").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/02/27 16:45
S109	2	("5600541" "5952714").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/02/27 16:47
S110	1	("5491362").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/02/27 16:48
S111	15	("4421985" "4742182" "5233174" "5352852" "5357056" "5493391" "5600541" "5729038" "5864381" "5867368" "6011294" "6117193" "6147389" "6274927" "6335224").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/02/27 16:49
S112	11	("4742182" "5352852" "5357056" "5493391" "5600541" "5729038" "5864381" "5867368" "5952714" "6117193" "6335224").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/02/27 16:49
S113	26	("4256945" "4448306" "4623401" "4695713" "4701587" "4717814" "4745264" "4769525" "4792683" "5010233" "5117279" "5175409" "5194695" "5239806" "5418189" "5498899" "5500555" "5521426" "5596171" "5598031" "5673845" "5840599" "5938956" "6111220" "6339210" "6426484").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/02/27 16:50
S114	11181	(lid cover) with (solder ball bump) with (device chip die IC circuit)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/27 16:52

S115	7494	S114 and S96	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/27 16:53
S116	28168864	@ad<"20040316"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/27 19:35
S117	11181	(lid cover) with (solder ball bump) with (device chip die IC circuit)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/27 19:35
S118	7494	S117 and S116	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/27 19:35
S119	2711	S118 and protect\$3	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/27 19:35
S120	1735	S119 and substrate	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/27 19:36
S121	1316	S120 and packag\$3	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/27 19:37
S122	1046	S121 and semiconductor	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/27 19:39
S123	462	S122 and (project\$3 protrud \$3 pillar)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/02/27 19:40

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